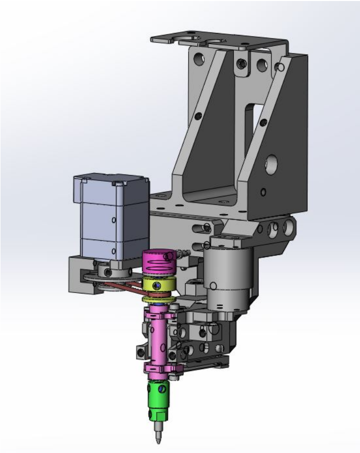
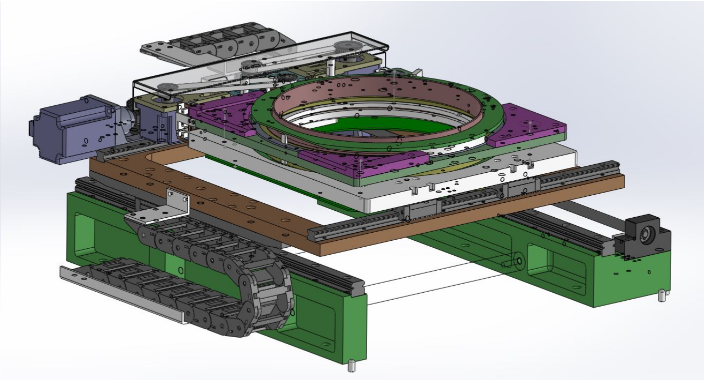
# AUTOMATION TECHNOLOGY CENTER PTE LTD

Automation Technology Center 's Die Bonder is first in industry to incorporate Ethercat Technology. With proven easy maintenance, highly available cross reference critical spare parts, and reliability, DB1200EP secures customer's investment in years to come.



Rotary Head with Spring Plate



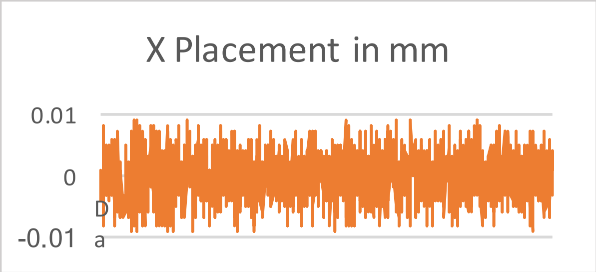
Wafer Table Design without Overhang

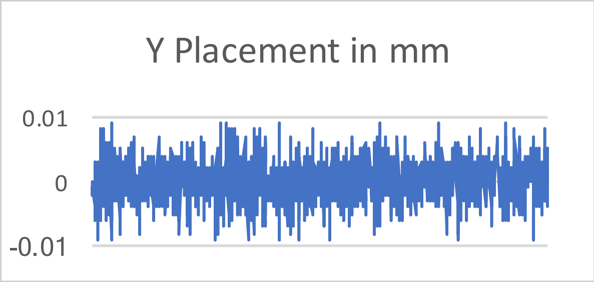
## SCALABLE & CONFIGURABLE

- Customisable Vision to cater for specific device requirements
- Modular & Upgradeable in future
- Industry Standard Real-time Ethercat

## OPERATION, MAINTENANCE & OWNERSHIP

- Easy to maintain critical axes;
- Easy troubleshooting by using Ethercat architecture;
- Easy Operation with Touch-screen





## SPEED AND ACCURACY

- 18K Dry cycle UPH
- 10 micron 3 sigma at 11K UPH
- Rotary Pick and Place

## Machine Dimensions

- Width x Depth x Height: 1110 x 1200 x 1620mm
- Weight: approximately 1100kg

## Supply Requirements

- Voltage: 200-230VAC 50/60Hz
- Current: 10A
- Compressed Air: 7 bar
- Vacuum: -0.75 bar

## Wafer & Die Dimensions

- Wafer: 4” to 8”
- Die Size: 0.15mm - 10 mm

## Leadframe Size

- Width: 20mm - 100mm
- Reel to Reel
- Thickness: 0.1 - 1 mm

## Bonding/Epoxy Process

- Bond force: 40gram to 100gram
- Bond Rotation: +/-180 degrees
- Epoxy Writing, Dotting, or Stamping

## Accuracy

- X,Y: +/-10 micron 3 sigma, Theta 3 deg 3 sigma
- MTBF > 200h